RELIABILITY REPORT

FOR

MAX9032AKA+

PLASTIC ENCAPSULATED DEVICES

October 27, 2008

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Quality Assurance
Director, Reliability Engineering

Conclusion

The MAX9032AKA+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

Table of Contents

I. Device Description

A. General

The MAX9030/MAX9031/MAX9032/MAX9034 single/dual/quad comparators are optimized for single-supply applications from +2.5V to +5.5V but can also be operated from dual supplies. These comparators have a 188ns propagation delay and consume 35µA of supply current per comparator over the -40°C to +125°C operating temperature range. The combination of low-power, single-supply operation down to +2.5V, and ultra-small footprint makes these devices ideal for portable applications. The MAX9030 is a low-cost single comparator with shutdown. The MAX9031, MAX9032, and MAX9034 are low-cost single, dual, and quad comparators without shutdown, respectively. The comparators' 4mV of built-in hysteresis provides noise immunity and prevents oscillations even with a slow-moving input signal. The input common-mode range extends from the negative supply to within 1.1V of the positive supply. The design of the comparator output stage substantially reduces switching current during output transitions, virtually eliminating power-supply glitches. The MAX9030 single comparator with shutdown is available in the space-saving 6-pin SC70 and SOT23 packages. The MAX9031 single comparator is available in tiny 5-pin SC70 and SOT23 packages. The MAX9032 dual comparator is available in 8-pin SOT23 and µMAX® packages, and the MAX9034 quad comparator is available in a 14-pin TSSOP package.

II. Manufacturing Information

A. Description/Function:	Low-Cost, Ultra-Small, Single/Dual/Quad Single-Supply Comparators
B. Process:	S12
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon, California or Texas
E. Assembly Location:	Carsem Malaysia
F. Date of Initial Production:	October 21, 2000

III. Packaging Information

A. Package Type:	8-pin SOT23
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1501-0206
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Jb:	110*°C/W
K. Single Layer Theta Jc:	80°C/W

IV. Die Information

A. Dimensions:	70 X 24 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	1.2 microns (as drawn)
F. Minimum Metal Spacing:	1.2 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are pending. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 790 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 1.36 \times 10^{-9}$

$\lambda = 1.36$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at http://www.maxim-ic.com/. Current monitor data for the S12 Process results in a FIT Rate of 1.36 @ 25C and 23.51 @ 55C, data limited (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The CM52 die type has been found to have all pins able to withstand a HBM transient pulse of 2500 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of 250 mA.

Table 1
Reliability Evaluation Test Results

MAX9032AKA+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	790	0
Moisture Testing (Note 2)				
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data